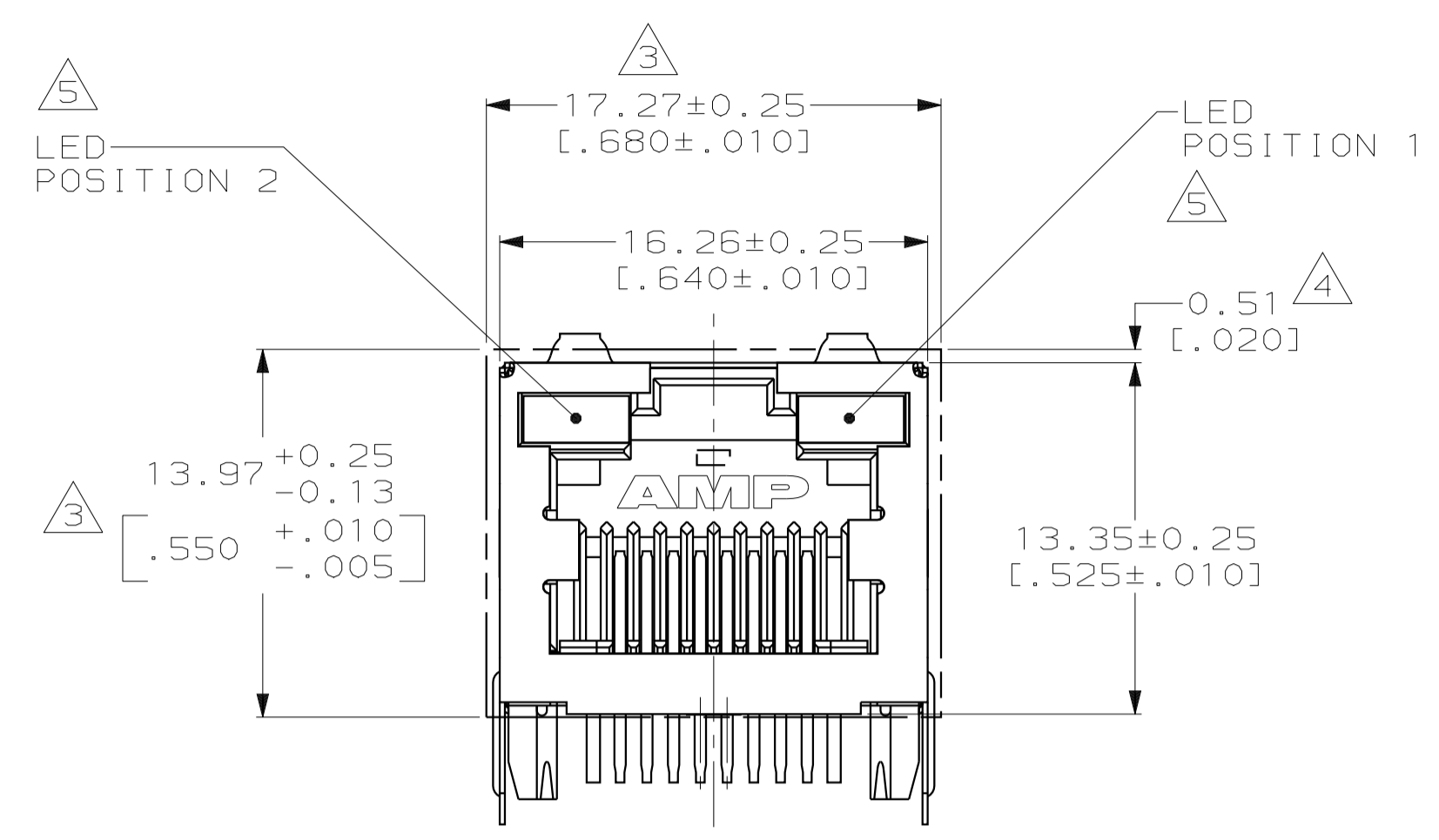
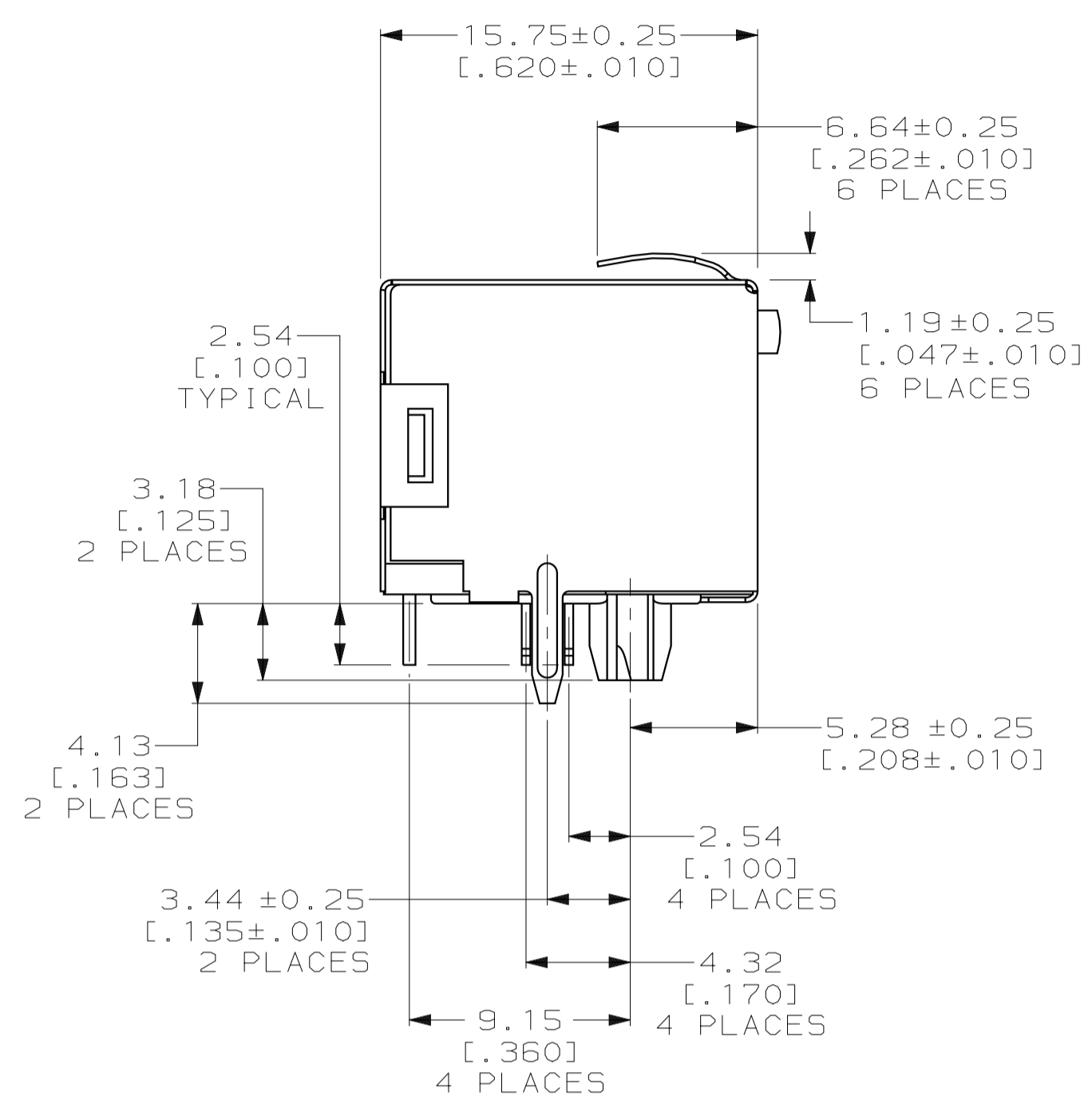
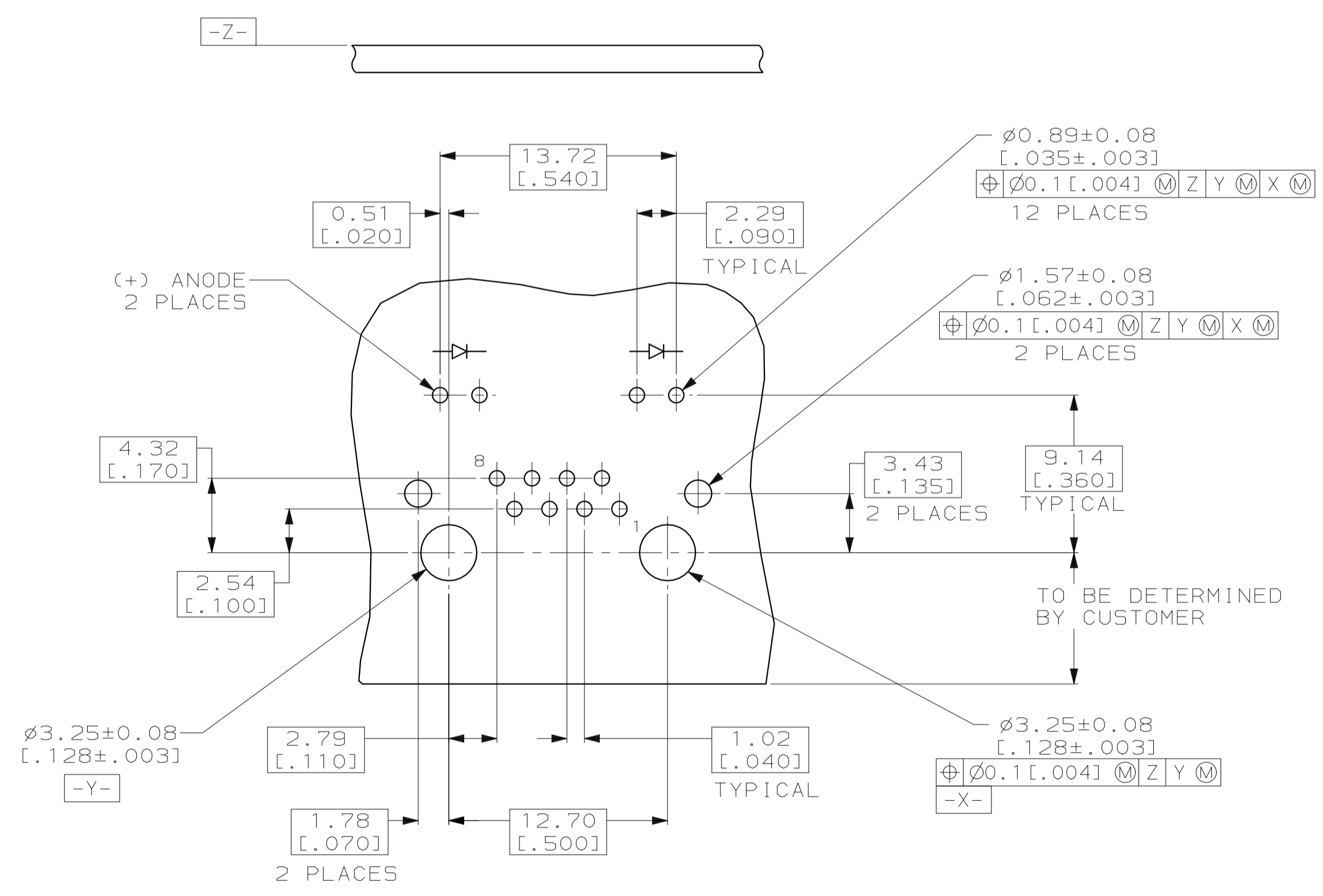


LOC		DIST		REVISIONS			
AA	22	REV	DATE	BY	CHK	APPV	
0		RELEASED PER EC 0511-0185-04	140C12004	BK	SF		



- △ MATERIAL: HOUSING - HIGH TEMPERATURE NYLON, HEAT DEFLECTION TEMPERATURE RATING 278°C [532°F] AT 1.8MPa [264 PSI], BLACK, UL94V-0. TERMINALS - 0.36[.014] THICK PHOS BRONZE PLATED WITH 3.81µm[.000150] MINIMUM THICK TIN IN SOLDER AREA, 1.27µm [.000050] MINIMUM GOLD IN LOCALIZED PLATE AREA. ENTIRE TERMINAL PLATED WITH 1.27µm [.000050] MINIMUM THICK NICKEL. SHIELD - 0.196[.0077] THICK COPPER ZINC ALLOY PREPLATED WITH 1.27µm[.000050] MINIMUM SATIN NICKEL WITH 2.03µm[.000080] MINIMUM SnAgCu POST DIPPED ON PCB GROUND TABS. LIGHT EMITTING DIODE (LED) - DIFFUSED EPOXY LENS, 0.51 x 0.51[.020 x .020] CARBON STEEL WIREFRAME LEADS PREPLATED WITH 2.29µm[.000090] SILVER OVER 1.02µm[.000040] NICKEL UNDERPLATE OVER 2.03µm[.000080] COPPER UNDERPLATE. POST-PLATED WITH 6.35µm [.000250] MINIMUM TIN. LEDS NOT DESIGNED FOR IR REFLOW SOLDERING.
- 2. JACK CAVITY CONFORMS TO FCC RULES AND REGULATIONS PART 68, SUBPART F.
- △ SUGGESTED PANEL OPENING DIMENSIONS.
- △ SUGGESTED CLEARANCE BETWEEN TOP OF CONNECTOR AND TOP PANEL OPENING.
- △ SEE TABLE FOR COLOR OF LEDS AND NUMBER REQUIRED.
- 6. TRAY PACKAGED.



SUGGESTED PRINTED CIRCUIT BOARD LAYOUT (COMPONENT SIDE)

INDICATOR COLOR	PART NUMBER
GREEN	6116615-5
GREEN	6116615-4
POSITION 2	POSITION 1

THIS DRAWING IS A CONTROLLED DOCUMENT.

DWN	B KUHNLY	140C12004	AMP Incorporated Harrisburg, PA 17105-3608
CHK	B KUHNLY	140C12004	
APPV	S FLICKINGER	140C12004	NAME INVERTED MODULAR JACK ASSEMBLY, 1X1, SHIELDED, TOP PANEL GROUNDS, LEDS, TIN PLATED SOLDER TAILS
PRODUCT SPEC	108-1163-4		
APPLICATION SPEC	114-2154		SIZE
MATERIAL	FINISH	WEIGHT	SCALE
△	△	△	4:1

CUSTOMER DRAWING